TECHNICAL DATA SHEET **Nov’21 Rev 1.5**

IMT-TE1100B
NON-CONDUCTIVE B-STAGE ADHESIVE

IMT-TE1100B is a single component, inorganic filled B-stage adhesive. This thermally conductive B-stage adhesive is designed for heat-sink applications. It has an excellent adhesion strength to various metals. This thermally conductive B-stage adhesive does not contains any prohibited and/or hazardous substances, is solventless and a 100% solid system. It complies to RoHS3, EU directive 2015/863 as well as Substances of Very High Concern (SVHC) published by ECHA.

IMT-TE1100B is packed in syringes for use in automated, high speed dispensing equipment or in jar for manually applied method.

TYPICAL PROPERTIES*

Cure Conditions (Actual holding temperature & time)	B Stage: 110˚C for 30 mins Post Cure: 150°C for 60 mins

Pot Life	4 days at room temperature
Shelf Life	12 months at -40°C

Physical Properties

Color	Light grey before & after cure
Consistency	Smooth, thixotropic paste
Specific Gravity	2.13
Viscosity @25˚C, 5rpm	30,000cPs
Thixotropic Index, (0.5/5rpm)	2.34
Glass Transition Temperature	> 100˚C
Shore D Hardness	85
Die Shear Strength	> 15Kgf per 3.5x2mm chip on FR4 substrate
Operating Temperature	-40˚C to +150°C

Electrical & Thermal Properties

Volume resistivity	> 1 x 10**14Ωcm
Thermal conductivity	0.8W/mK

Ionic Contents

Chloride, Cl-	< 100ppm
Sodium, Na+	< 20ppm
Potassium, K+	< 20ppm
Ammonium, NH4+	< 20ppm

IN-MAT TECHNOLOGIES (S) PTE LTD
623 ALJUNIED ROAD, #05-09, ALJUNIED INDUSTRIAL COMPLEX
SINGAPORE 389835
Tel / Whatsapp / Wechat: +65-8688 8711
E-Mail: sales@inmat-tech.com
Website: www.inmat-tech.com

* The information is based on data and tests believed to be accurate. In-Mat Technologies (S) Pte Ltd makes no warranties as to its accuracy and assumes no liability in connection with the use or inability to use this product.